

AMENDMENTS TO THE CLAIMS

The claims in this listing will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Original) An arrangement for increasing the packing density on a printed circuit (1) with surface mounted electrical components (2), with the printed circuit (1) being formed by two films (3x, 3y) which are pressed against one another with a dielectric (4) arranged between them, and with at least one of the mutually opposite faces (3a, 3b) of the films (3x, 3y) being fitted with surface mounted electrical components (2), **characterized** in that via holes (6b) are provided in the printed circuit (1) in order to connect the two films (3x, 3y), with each via hole (6b) being a direct connection between the mutually opposite faces (3a, 3b) of the films (3x, 3y).
2. (Original) The arrangement as claimed in claim 1, **characterized** in that further surface mounted electrical components (2) are arranged on the faces (3c, 3d) of the films (3x, 3y) which are not mutually opposite.
3. (Amended) The arrangement as claimed in ~~one of the preceding claims~~claim 1, **characterized** in that a further layer of a dielectric (4) as well as a further film (3z) are applied to at least one face (3c, 3d) of the printed circuit (1).

4. (Amended) The arrangement as claimed in ~~one of the preceding claims~~ claim 1, **characterized** in that the films (3x, 3y, 3z) contain copper.
5. (Amended) The arrangement as claimed in ~~one of the preceding claims~~ claim 1, **characterized** in that the printed circuit (1) has first contacts (6a) which are formed on at least one face (3c, 3d) of the printed circuit (1).
6. (Amended) The arrangement as claimed in ~~one of claims 3-5~~ claim 3, **characterized** in that via holes (6c) are formed between the compressed films (3x, 3y) and the further film (3z).
7. (Amended) The arrangement as claimed in ~~one of the preceding claims~~ claim 1, **characterized** in that the surface mounted electrical components (2) are resistors, coils or capacitors.
8. (Amended) A stack having a plurality of printed circuits (1) as claimed in ~~one of the preceding claims~~ claim 1 arranged one on top of the other.
9. (New) The arrangement as claimed in claim 4, **characterized** in that via holes (6c) are formed between the compressed films (3x, 3y) and the further film (3z).

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10 (New) The arrangement as claimed in claim 5, **characterized** in that via holes (6c) are formed between the compressed films (3x, 3y) and the further film (3z).